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December 2013

FQP2N60C / FQPF2N60C

N-Channel QFET® MOSFET

600 V, 2 A, 4.7 Ω

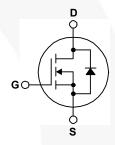
Description

This N-Channel enhancement mode power MOSFET is • 2 A, 600 V, $R_{DS(on)}$ = 4.7 Ω (Max.) @ V_{GS} = 10 V, produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state • Low Gate Charge (Typ. 8.5 nC) resistance, and to provide superior switching performance • Low Crss (Typ. 4.3 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power • 100% Avalanche Tested factor correction (PFC), and electronic lamp ballasts.

Features







Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQP2N60C	FQPF2N60C	Unit
V_{DSS}	Drain-Source Voltage		600		V
I _D	Drain Current - Continuous (T _C = 25°C)		2.0	2.0 *	Α
	- Continuous (T _C = 100°C)	F	1.35	1.35 *	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	8	8 *	Α
V _{GSS}	Gate-Source Voltage		± 30		V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	120		mJ
I _{AR}	Avalanche Current	(Note 1)	2.0		Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.4		mJ
dv/dt	Peak Diode Recovery dv/dt (No		4.5		V/ns
P_{D}	Power Dissipation (T _C = 25°C)		54	23	W
	- Derate above 25°C		0.43	0.18	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C
T _L	Maximum Lead Temperature for Soldering,		300		°C
	1/8" from Case for 5 Seconds				C

^{*} Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FQP2N60C	FQPF2N60C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.32	5.5	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ, Max.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP2N60C	FQP2N60C	TO-220	Tube	N/A	N/A	50 units
FQPF2N60C	FQPF2N60C	TO-220F	Tube	N/A	N/A	50 units

Flactrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	600			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.6		V/°C
I _{DSS} Zero Ga	Zana Oata Valtana Basin Ourset	V _{DS} = 600 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 480 V, T _C = 125°C			10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0		4.0	V
r _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 1 A		3.6	4.7	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 1 A		5.0		S
Dynam	ic Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		180	235	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		20	25	pF
C _{rss}	Reverse Transfer Capacitance			4.3	5.6	pF
Switch	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 300 V, I _D = 2 A,		9	28	ns
t _r	Turn-On Rise Time	$V_{DD} = 300 \text{ V}, I_D = 2 \text{ A},$ $R_G = 25 \Omega$		25	60	ns
t _{d(off)}	Turn-Off Delay Time	NG - 20 32		24	58	ns
t _f	Turn-Off Fall Time	(Note 4)		28	66	ns
Qg	Total Gate Charge	V _{DS} = 480 V, I _D = 2 A,		8.5	12	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	/	1.3		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		4.1		nC
	Source Diode Characteristics an					
l _S	Maximum Continuous Drain-Source Diode Forward Current				2	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				8	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 2 A			1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_S = 2 \text{ A,}$		230	//	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		1.0		μС

- Notes: 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 56 mH, I_{AS} = 2 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. I_{SD} \leq 2 A, di/dt \leq 200 A/ μ s, V_{DD} \leq BV_{DSS}, starting T_{J} = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

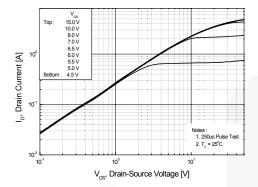


Figure 1. On-Region Characteristics

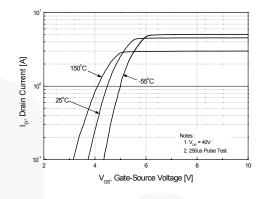


Figure 2. Transfer Characteristics

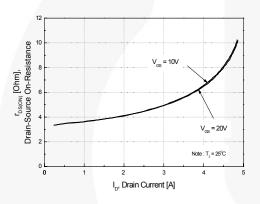


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

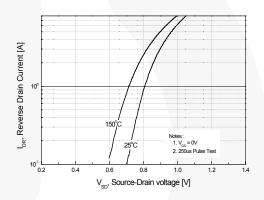


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

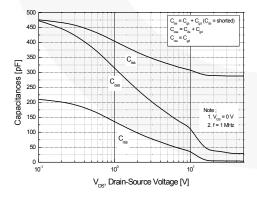


Figure 5. Capacitance Characteristics

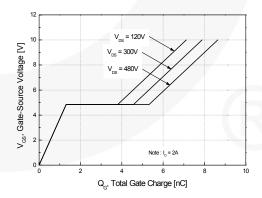


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

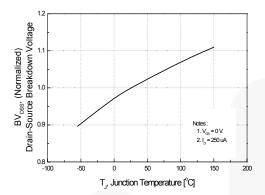


Figure 7. Breakdown Voltage Variation vs Temperature

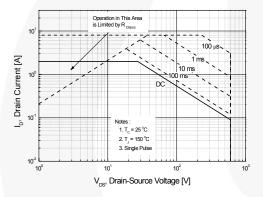


Figure 9-1. Maximum Safe Operating Area for FQP2N60C

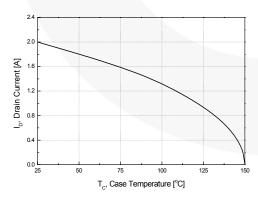


Figure 10. Maximum Drain Current vs Case Temperature

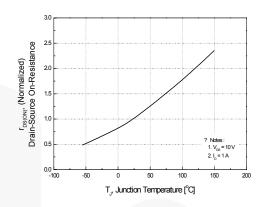


Figure 8. On-Resistance Variation vs Temperature

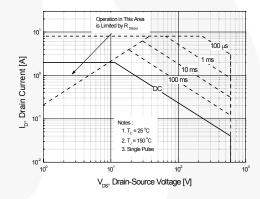


Figure 9-2. Maximum Safe Operating Area for FQPF2N60C

Typical Characteristics (Continued)

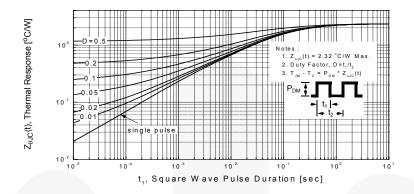


Figure 11-1. Transient Thermal Response Curve for FQP2N60C

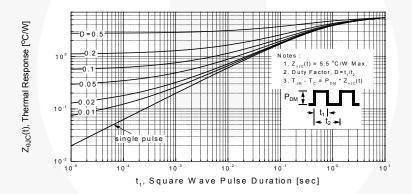


Figure 11-2. Transient Thermal Response Curve for FQPF2N60C

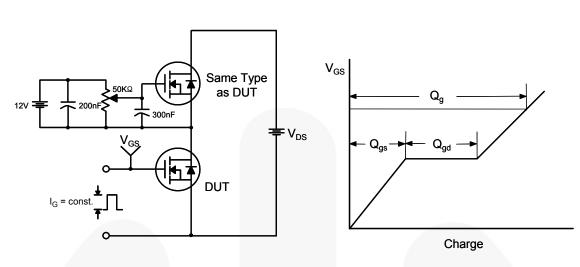


Figure 12. Gate Charge Test Circuit & Waveform

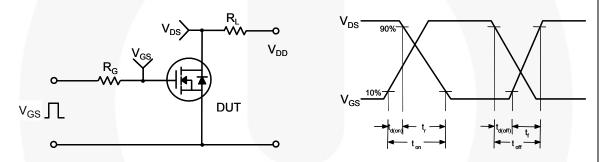


Figure 13. Resistive Switching Test Circuit & Waveforms

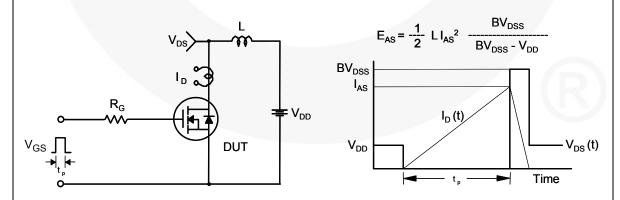
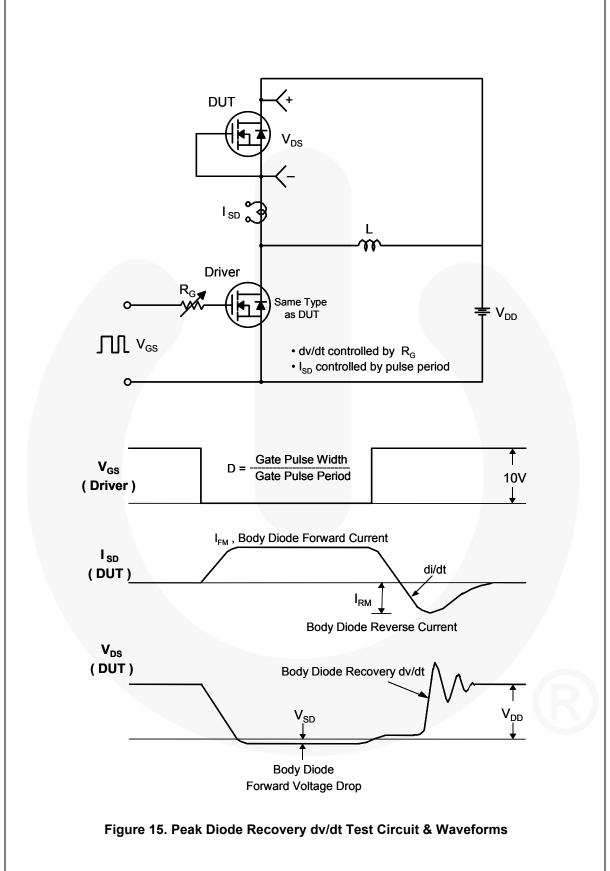


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

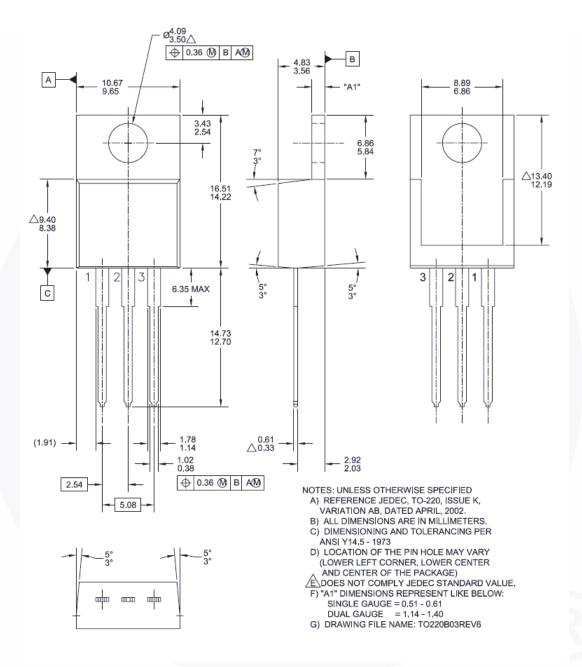


Figure 16. TO-220, Molded, 3-Lead, Jedec Variation AB

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Mechanical Dimensions

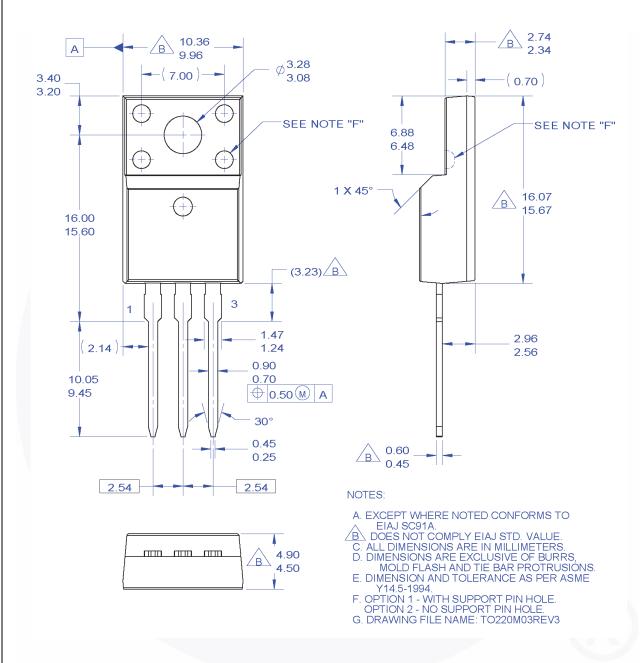


Figure 17. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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